

Title (en)

Method for sealing a device such as an induction coil, and mould for carrying out the method.

Title (de)

Verfahren zum Abdichten einer Vorrichtung wie eine Induktionspule, und Form zur Durchführung des Verfahrens.

Title (fr)

Procédé d'étanchéification d'une pièce telle qu'une bobine d'induction et moule pour la mise en oeuvre du procédé.

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Application

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Abstract (en)

Method for sealing a device such as an induction coil and mould for carrying out the method. The subject of the invention is a method for sealing a device such as an induction coil. For this purpose, the device is shrouded in a heat-settable vinyl resin (3). <IMAGE>

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Citation (search report)

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